IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005, IPC.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					Materials	and Mfg I	nformatic	on	
Supplier Infor	mation														
Company name*			Company un	Company unique ID			Unique ID Authority					Response Date*			
onsemi												2024-05-08			
Contact Name			Title - Contact			P	Phone - Contact*					Email - Contact*			
Product-Env-Stev	wards	Product Enviro Compliance			r	NA NA				P	Product-Env-Stewards@onsemi.com				
uthorized Repres	sentative*	Title - Representative			P	Phone - Representative*				E	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			ı	NA				P	Product-Env-Stewards@onsemi.com			
Reques	quester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date	e Version	N	Manufacturing Site		Wei	ght*	UOM	Unit Type
		NCV5702DR2G Orderable Part		Orderable Part nu	umber of NCV5702	NCV5702DR2G. 2024-05		-08 PH1			150.56		mg	Each	
Ianufacturing	g Proccess Information	1						,		_		,			
Termina	nal Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MSL Rating		Peak Process Body Temperatu		emperatur	re Max Time at Peak Temper		mperature	ture Number of Reflow Cycles		eles
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy		1		260		С	30		seconds	3		
Comments															
vel 1 - maximum	time at peak temperature d	luring sol	dering is 10-3	0 seconds											
or more informa	tion regarding material com	position	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.58	mg	Supplier	Silicon (Si)	7440-21-3		1.58	mg
Die Attach	0.25	mg		Epoxy resin	proprietary data		0.025	mg
			Supplier	Silver (Ag)	7440-22-4		0.2	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.025	mg
Lead Frame	53.79	mg	Supplier	Zinc (Zn)	7440-66-6		0.0645	mg
			Supplier	Iron (Fe)	7439-89-6		1.2641	mg
			Supplier	Copper (Cu)	7440-50-8		52.4453	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0161	mg
Mold Compound-Black	94.04	mg		Epoxy resin	proprietary data		7.053	mg
			Supplier	Phenolic Resin	Proprietary Data		2.351	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		7.053	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4702	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		77.1128	mg
Plating	0.75	mg	Supplier	Palladium (Pd)	7440-05-3		0.0525	mg
			В	Nickel (Ni)	7440-02-0		0.612	mg
			Supplier	Gold (Au)	7440-57-5		0.0855	mg
Wire Bond - Au	0.15	mg	Supplier	Gold (Au)	7440-57-5		0.15	mg